

PHP/PHB143NQ04T

N-channel TrenchMOS™ standard level FET

Rev. 01 — 13 May 2004

Product data

1. Product profile

1.1 Description

N-channel enhancement mode field-effect transistor in a plastic package using TrenchMOS™ technology.

1.2 Features

- Standard level threshold
- Very low on-state resistance.

1.3 Applications

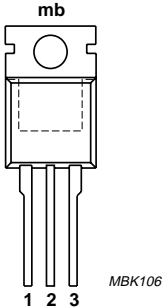
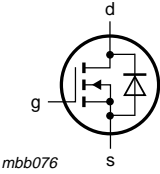
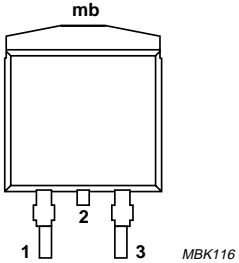
- Motors, lamps, solenoids
- DC-to-DC converters
- Uninterruptible power supplies
- General industrial applications.

1.4 Quick reference data

- $V_{DS} \leq 40$ V
- $I_D \leq 75$ A
- $P_{tot} \leq 200$ W
- $R_{DSon} \leq 5.2$ m Ω .

2. Pinning information

Table 1: Pinning - SOT78 (TO-220AB) and SOT404 (D²-PAK), simplified outline and symbol

Pin	Description	Simplified outline	Symbol
1	gate (g)		
2	drain (d) [1]		
3	source (s)		
mb	mounting base; connected to drain (d)		
		SOT78 (TO-220AB)	SOT404 (D²-PAK)

[1] It is not possible to make connection to pin 2 of the SOT404 package



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3. Ordering information

Table 2: Ordering information

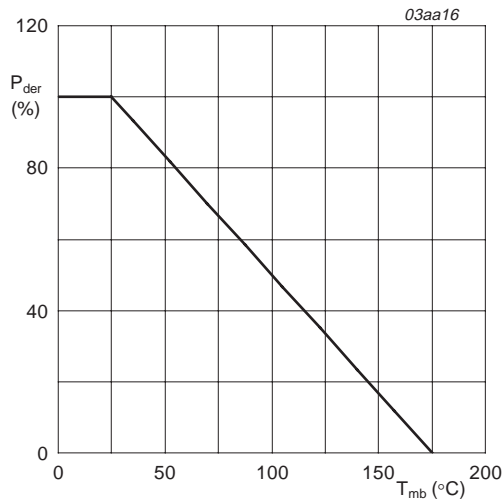
Type number	Package		Version
	Name	Description	
PHP143NQ04T	TO-220AB	Plastic single-ended package; heatsink mounted; 1 mounting hole; 3 leads	SOT78
PHB143NQ04T	D ² -PAK	Plastic single-ended surface mounted package; 3 leads (one lead cropped)	SOT404

4. Limiting values

Table 3: Limiting values

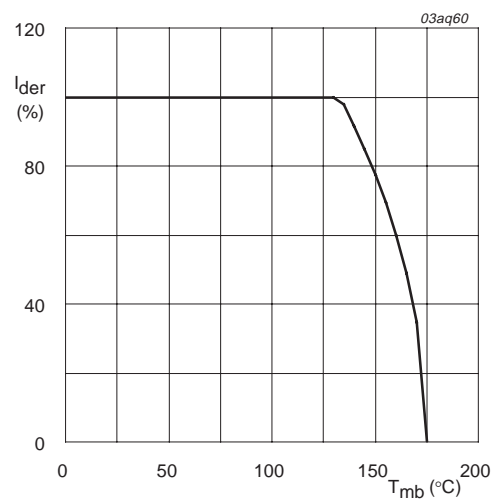
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V _{DS}	drain-source voltage (DC)	25 °C ≤ T _j ≤ 175 °C	-	40	V
V _{DGR}	drain-gate voltage (DC)	25 °C ≤ T _j ≤ 175 °C; R _{GS} = 20 kΩ	-	40	V
V _{GS}	gate-source voltage (DC)		-	±20	V
I _D	drain current (DC)	T _{mb} = 25 °C; V _{GS} = 10 V; Figure 2 and 3	-	75	A
		T _{mb} = 100 °C; V _{GS} = 10 V; Figure 2	-	75	A
I _{DM}	peak drain current	T _{mb} = 25 °C; pulsed; t _p ≤ 10 μs; Figure 3	-	240	A
P _{tot}	total power dissipation	T _{mb} = 25 °C; Figure 1	-	200	W
T _{stg}	storage temperature		-55	+175	°C
T _j	junction temperature		-55	+175	°C
Source-drain diode					
I _S	source (diode forward) current (DC)	T _{mb} = 25 °C	-	75	A
I _{SM}	peak source (diode forward) current	T _{mb} = 25 °C; pulsed; t _p ≤ 10 μs	-	240	A
Avalanche ruggedness					
E _{DS(AL)S}	non-repetitive drain-source avalanche energy	unclamped inductive load; I _D = 69 A; t _p = 0.27 ms; V _{DD} ≤ 40 V; R _{GS} = 50 Ω; V _{GS} = 10 V; starting at T _j = 25 °C	-	475	mJ



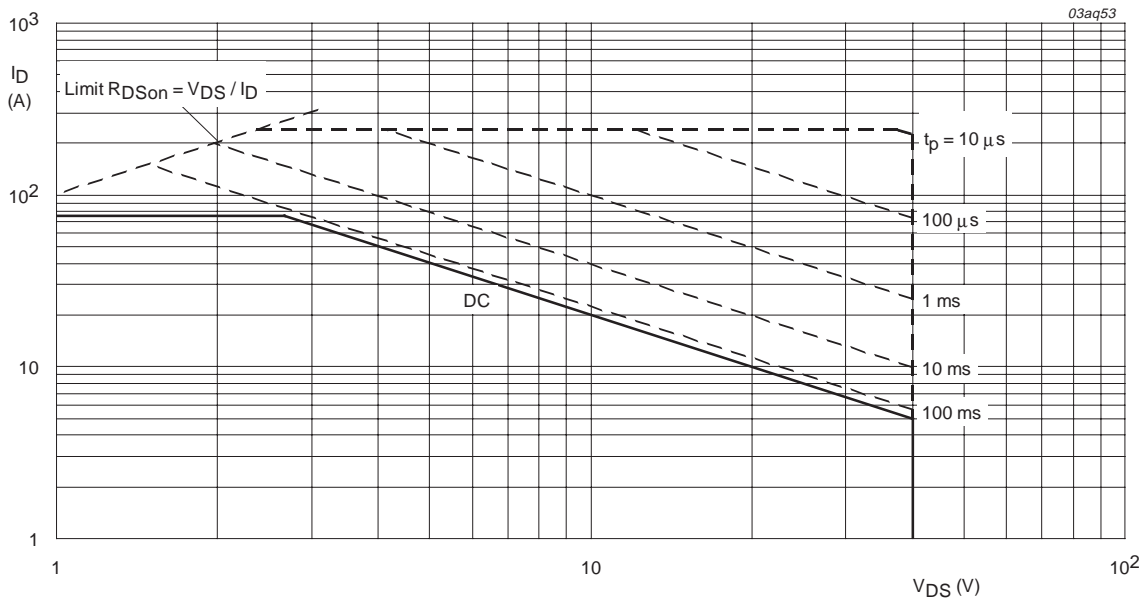
$$P_{der} = \frac{P_{tot}}{P_{tot(25^{\circ}C)}} \times 100\%$$

Fig 1. Normalized total power dissipation as a function of mounting base temperature.



$$I_{der} = \frac{I_D}{I_{D(25^{\circ}C)}} \times 100\%$$

Fig 2. Normalized continuous drain current as a function of mounting base temperature.



T_{mb} = 25 °C; I_{DM} is single pulse; V_{GS} = 10 V.

Fig 3. Safe operating area; continuous and peak drain currents as a function of drain-source voltage.

5. Thermal characteristics

Table 4: Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	Figure 4	-	-	0.75	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient					
	SOT78	vertical in still air	-	60	-	K/W
	SOT404	mounted on a printed-circuit board; minimum footprint.	-	50	-	K/W

5.1 Transient thermal impedance

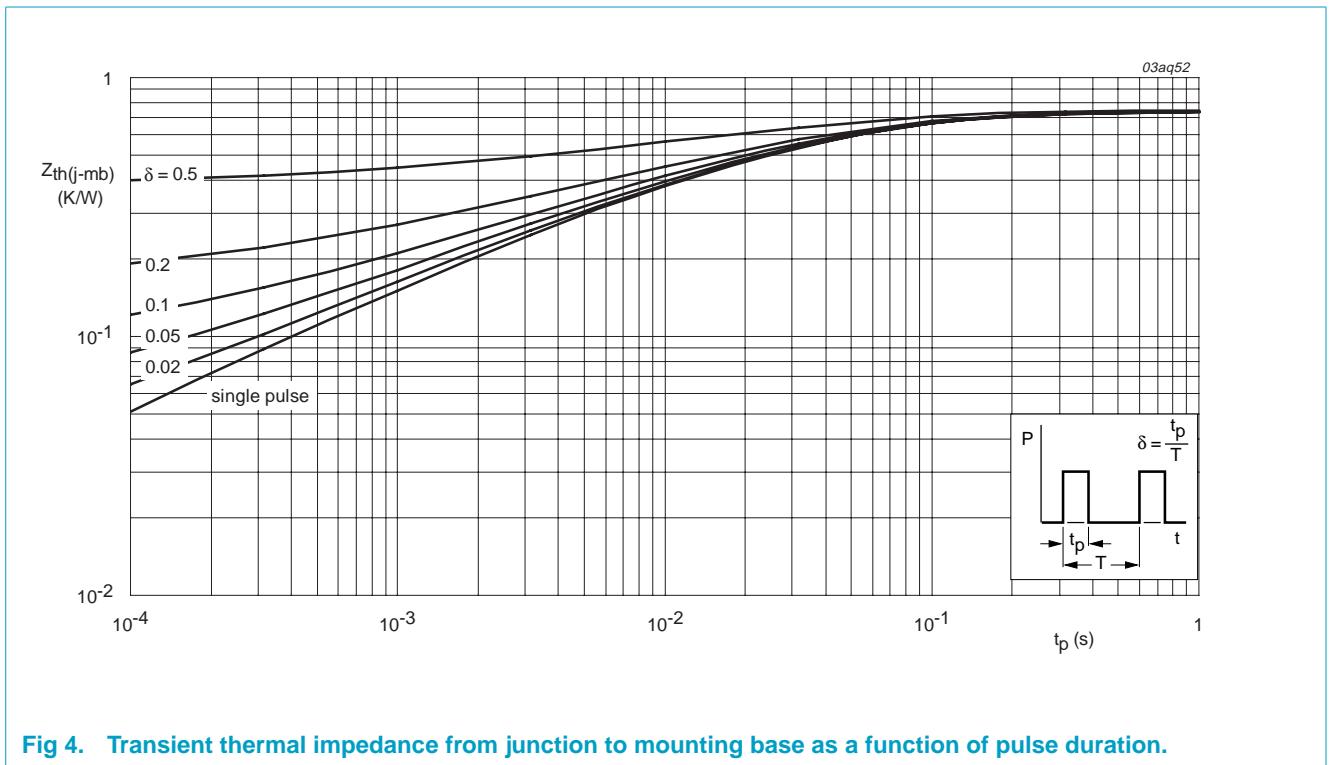


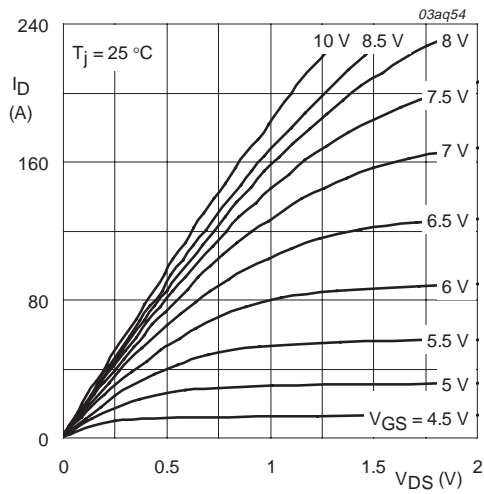
Fig 4. Transient thermal impedance from junction to mounting base as a function of pulse duration.

6. Characteristics

Table 5: Characteristics

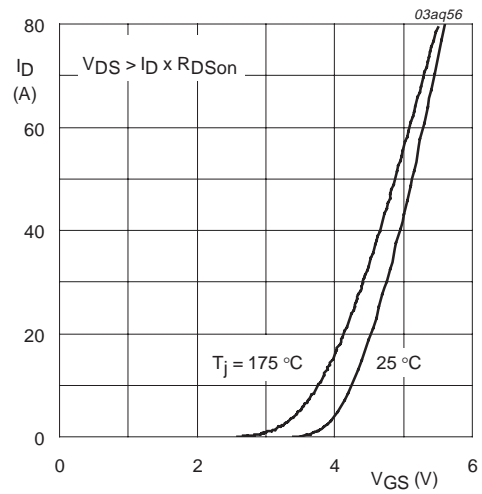
$T_j = 25\text{ °C}$ unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static characteristics						
$V_{(BR)DSS}$	drain-source breakdown voltage	$I_D = 250\text{ }\mu\text{A}$; $V_{GS} = 0\text{ V}$ $T_j = 25\text{ °C}$	40	-	-	V
		$T_j = -55\text{ °C}$	36	-	-	V
$V_{GS(th)}$	gate-source threshold voltage	$I_D = 1\text{ mA}$; $V_{DS} = V_{GS}$; Figure 9 and 10 $T_j = 25\text{ °C}$	2	3	4	V
		$T_j = 175\text{ °C}$	1	-	-	V
		$T_j = -55\text{ °C}$	-	-	4.4	V
I_{DSS}	drain-source leakage current	$V_{DS} = 40\text{ V}$; $V_{GS} = 0\text{ V}$ $T_j = 25\text{ °C}$	-	-	1	μA
		$T_j = 175\text{ °C}$	-	-	500	μA
I_{GSS}	gate-source leakage current	$V_{GS} = \pm 20\text{ V}$; $V_{DS} = 0\text{ V}$	-	2	100	nA
$R_{DS(on)}$	drain-source on-state resistance	$V_{GS} = 10\text{ V}$; $I_D = 25\text{ A}$; Figure 7 and 8 $T_j = 25\text{ °C}$	-	4.4	5.2	m Ω
		$T_j = 175\text{ °C}$	-	-	9.9	m Ω
Dynamic characteristics						
$Q_{g(tot)}$	total gate charge	$I_D = 25\text{ A}$; $V_{DD} = 32\text{ V}$; $V_{GS} = 10\text{ V}$; Figure 13	-	52	-	nC
Q_{gs}	gate-source charge		-	12	-	nC
Q_{gd}	gate-drain (Miller) charge		-	16	-	nC
C_{iss}	input capacitance	$V_{GS} = 0\text{ V}$; $V_{DS} = 25\text{ V}$; $f = 1\text{ MHz}$; Figure 11	-	2840	-	pF
C_{oss}	output capacitance		-	710	-	pF
C_{rss}	reverse transfer capacitance		-	295	-	pF
$t_{d(on)}$	turn-on delay time	$V_{DD} = 30\text{ V}$; $R_L = 1.2\text{ }\Omega$; $V_{GS} = 10\text{ V}$; $R_G = 10\text{ }\Omega$	-	15	-	ns
t_r	rise time		-	51	-	ns
$t_{d(off)}$	turn-off delay time		-	81	-	ns
t_f	fall time		-	56	-	ns
Source-drain diode						
V_{SD}	source-drain (diode forward) voltage	$I_S = 25\text{ A}$; $V_{GS} = 0\text{ V}$; Figure 12	-	0.85	1.2	V
t_{rr}	reverse recovery time	$I_S = 20\text{ A}$; $dI_S/dt = -100\text{ A}/\mu\text{s}$; $V_{GS} = 0\text{ V}$	-	85	-	ns
Q_r	recovered charge		-	38	-	nC



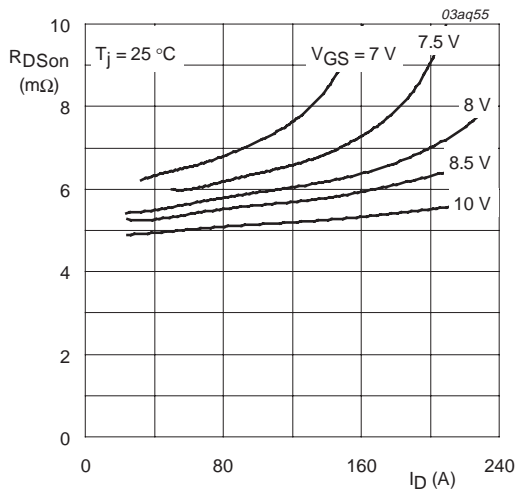
$T_j = 25\text{ °C}$

Fig 5. Output characteristics: drain current as a function of drain-source voltage; typical values.



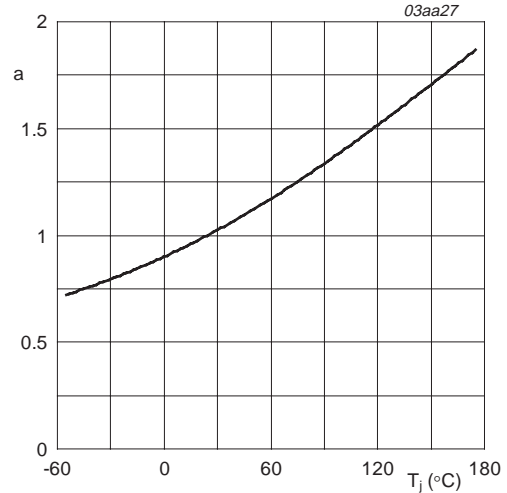
$T_j = 25\text{ °C}$ and 175 °C ; $V_{DS} > I_D \times R_{DSon}$

Fig 6. Transfer characteristics: drain current as a function of gate-source voltage; typical values.



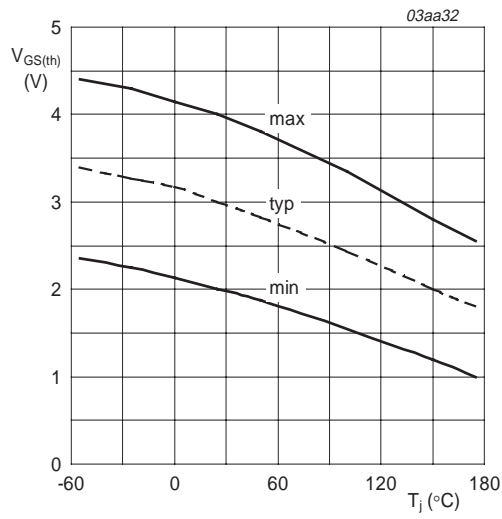
$T_j = 25\text{ °C}$

Fig 7. Drain-source on-state resistance as a function of drain current; typical values.



$$a = \frac{R_{DSon}}{R_{DSon}(25\text{ °C})}$$

Fig 8. Normalized drain-source on-state resistance factor as a function of junction temperature.



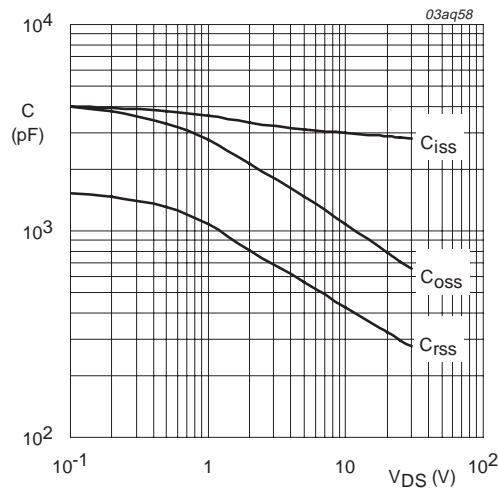
$I_D = 1 \text{ mA}; V_{DS} = V_{GS}$

Fig 9. Gate-source threshold voltage as a function of junction temperature.



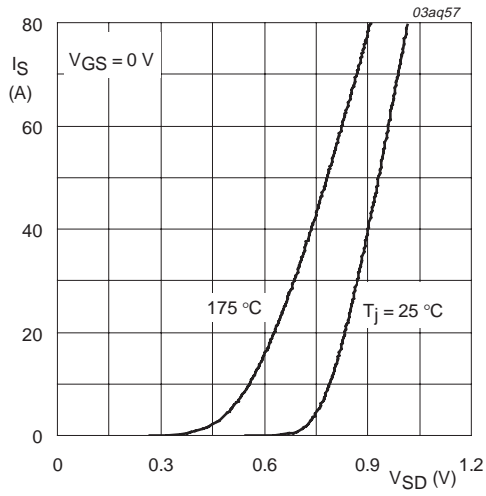
$T_j = 25 \text{ }^{\circ}C; V_{DS} = 5 \text{ V}$

Fig 10. Sub-threshold drain current as a function of gate-source voltage.



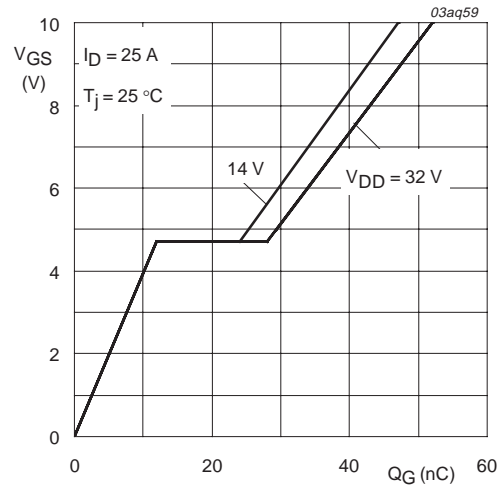
$V_{GS} = 0 \text{ V}; f = 1 \text{ MHz}$

Fig 11. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values.



$T_j = 25$ °C and 175 °C; $V_{GS} = 0$ V

Fig 12. Source (diode forward) current as a function of source-drain (diode forward) voltage; typical values.



$I_D = 25$ A; $V_{DD} = 14$ V and 32 V

Fig 13. Gate-source voltage as a function of gate charge; typical values.

7. Package outline

Plastic single-ended package; heatsink mounted; 1 mounting hole; 3-lead TO-220AB

SOT78



Fig 14. SOT78 (TO-220AB).

Plastic single-ended surface mounted package (Philips version of D²-PAK); 3 leads (one lead cropped)

SOT404

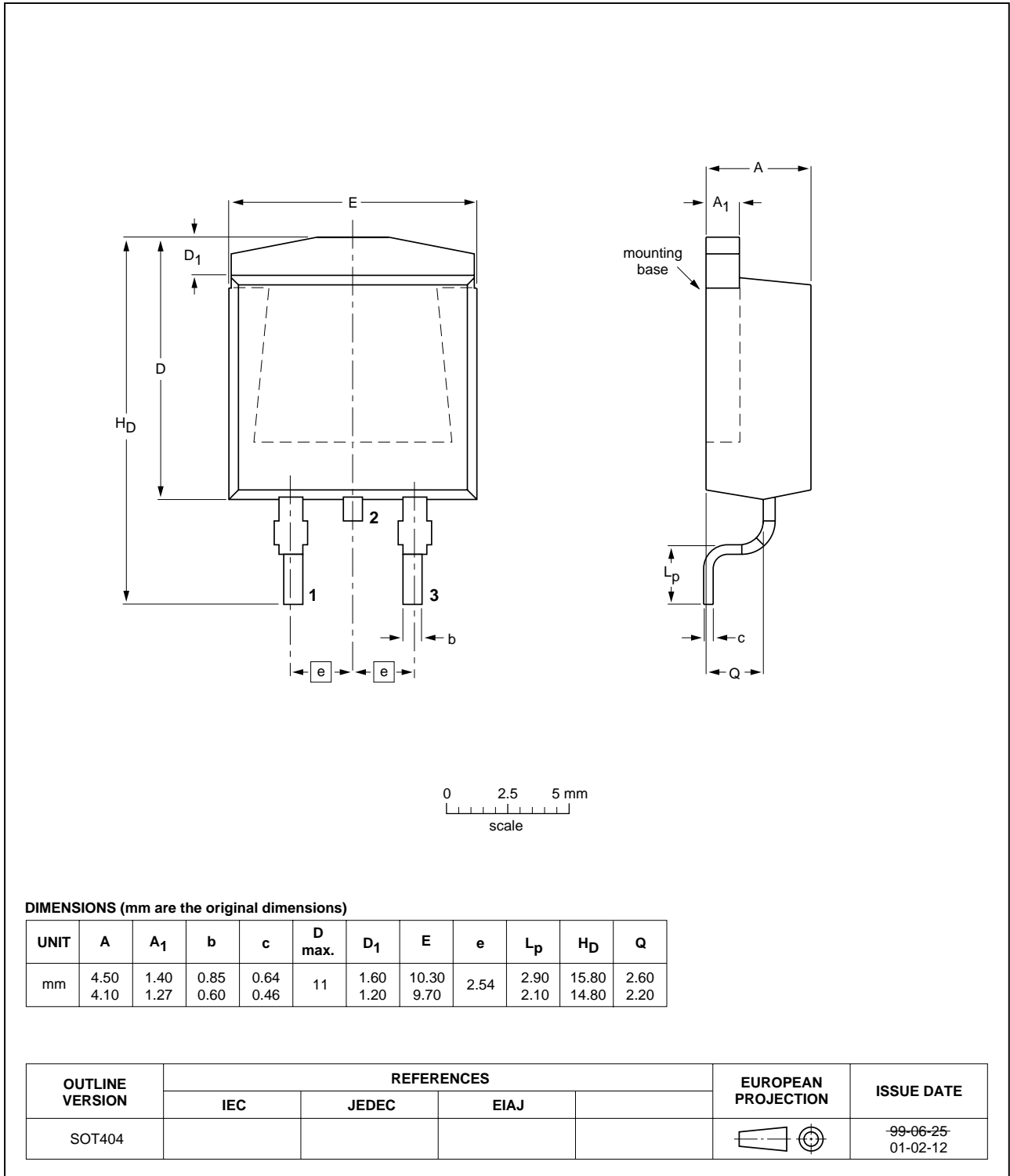


Fig 15. SOT404 (D²-PAK).

8. Revision history

Table 6: Revision history

Rev	Date	CPCN	Description
01	20040513	-	Product data (9397 750 13165).

9. Data sheet status

Level	Data sheet status ^[1]	Product status ^{[2][3]}	Definition
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
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[3] For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.

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